

Defense, Avionics, Space &

High Reliability Services







Mil-Standards

Custom Products

RF Testing Capabilities



Environmental Testing

Special Testing Capabilities









Johanson Companies

Johanson Dielectrics, Inc. and Johanson Technology, Inc. are located in Camarillo, California, and have over 50 years of experience specializing in the design and manufacture of high quality ceramic products. Johanson provides both Mil-Standard screening and COTS Ceramic Chip Capacitors, RF Passives, RF Inductors to high reliability applications globally.

In-House Testing Capabilities

In addition to manufacturing, the Camarillo facility has a complete High Reliability department with in-house testing capabilities.

Comprehensive Mil-Standard Testing Groups A, B & C

Electrical & Mechanical Inspections

- 100% Electrical Testing
- · Cap, DF, IR, DWV, Voltage Breakdown
- 100% Visual Inspection (Mil 883 Class K or S Options)
- Full Data on Serialized Units
- Hot IR Testing
- Temperature Capacitance Coefficient (TCC)
- Temperature Voltage Coefficient (TVC)





Analytical Testing

- Destructive Physical Analysis (DPA)
- Radiographic Inspection
- SEM Inspection
- Solderability Testing
- Acoustic Microscopy (Sonoscan) Inspection
- XRF Analysis

RF & Microwave Testing Expertise

- Vector Network Analyzer Measurements
- Resonant Line Measurements for ESR at Frequency

Simulation software and designer libraries.

Contact us with your high reliability needs.



- Burn In / Voltage Conditioning
- Life Testing
- · Class H, K or S Element Evaluation
- HALT / HASS Testing
- Humidity Testing
- Moisture Resistance
- Resistance to Solder Heat
- · Shear Test / Bond Pull Test
- Bend Testing
- Steam Age
- Temperature Cycling
- Thermal Shock Testing
- · Shock / Vibration Testing
- Wire Bond Testing



Available Termination Options

MLCC Termination Options

| Termination Type | Barrier to Prevent Solder Leaching | RoHS | Primary Applications | | | | | |
|-----------------------------|--|------|---|--|--|--|--|--|
| Ni/Sn | Ni | Yes | All solder applications where RoHS is required. This is Johanson's standard termination used by the largest number of customers. Most likely to be in stock at Johanson or at Johanson authorized distributors. | | | | | |
| Ni/SnPb | Ni | No | Military applications where the lead (Pb) mitigates Tin whisker growth. | | | | | |
| Flexterm Ni/Sn | Ni | Yes | Flexible terminations for high physical stress applications | | | | | |
| Flexterm Ni/SnPb | Ni | No | Flexible terminations for high physical stress applications | | | | | |
| Ni/Au Gold Termination | Ni | Yes | Parts are epoxied in place or a mix of solder and epoxy attachment is used. Controlled Au thickness to avoid Gold embrittlement issues when soldering. Premium price. | | | | | |
| Cu/Sn (Copper barrier) | Cu | Yes | This non-magnetic termination is best suited for application where very high inductance / magnetic fields are present. Use where RoHS is required. Most common non-magnetic termination. | | | | | |
| Cu/SnPb (Copper barrier) | Cu | No | This non-magnetic termination is best suited for application where very high inductance / magnetic fields are present. | | | | | |
| PdAg | None | Yes | No plating - solderable thick film PdAg alloy termination. Premium price. | | | | | |
| PtAg | None | Yes | No plating - solderable thick film PtAg alloy termination. Premium price. | | | | | |
| | | | | | | | | |

Single Layer Termination Options

| TiW/Ni/Au | Ni | Yes | Chip & Au wire where capacitor is soldered in place or a mix of solder and epoxy attachment is used. |
|-----------|------|-----|---|
| TiW/Au | None | Yes | Chip & Au wire where capacitor is epoxy attached. Optimum termination for wirebonding. Cannot solder this chip as substantial leaching will occur. |

Lead-Frame Termination Options

| Ni | None | Yes | Used in very high-temp applications |
|--------------------------|------|-----|--|
| Cu/Ni/SnPb | Ni | No | Typically used in military applications |
| CuSn6 Phosphor Bronze | Ni | No | SnPb plate |
| Iron-Nickel Alloy | Ni | Yes | Sn plate |
| Pure Silver Leads | None | Yes | Used in very high power RF. Premium price. |

Contact us to quote your custom lead materials and types.

Ask a Question

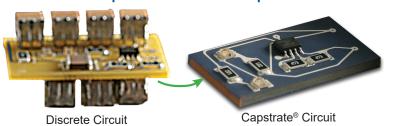
If you have unique needs or require additional technical information, contact your Johanson Representative : https://isotope-electronics.com/f/contact-fr

johansontechnology.com johansondielectrics.com johansontechnology.com johansontechnology.com johansondielectrics.com

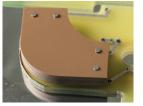
| Applications to Products Chart |) : | Thin E. | Actallized Single Lay | Plana Discoidal Substrates | High E Oiscoidal L. | High I, Tequency Elw, | Po MCC | High z Radiz | High Colass 1 | Safety, CASA, Class 2 Dic. | iffed MI CCs (1, seechics | SMPS NPO, X (250 VAC) | RF H. Stacked M. CCs | REIN POWER HIGH | Ed Page: | RF INC MCCs COMPONE | Sup. |
|--|--------|---------|-----------------------|----------------------------|---------------------|-----------------------|--------------------|--------------|---------------|----------------------------|---------------------------|-----------------------|----------------------|-----------------|----------|---------------------|---------|
| APPLICATIONS | Micro | Thin E | Plans | Planar & C | High E | High | 10/ Joji High J | High 7 | High | Safeti | Low L | Sello, JMS | RF L. Sta | RF IN | RF H. | AF MA | ouctors |
| RF Bypass / Decoupling | | | | | • | • | • | • | • | | • | • | | | | | |
| Connector / Cable Filters | | | • | • | | | • | • | | | • | | | • | | • | |
| Housing / Chassis Filters | | | • | • | | | | • | | | | | | | | | |
| Mains Filtering Certified | | | | | | | | • | | • | | | | | | | |
| Power Conditioning / Rail Filtering | | | | | • | • | • | • | • | • | | • | • | | | | |
| SwitchMode Power Supply Filtering | | | | | | | • | • | • | • | | • | | | | | |
| EMI / RFI Filtering | • | • | • | | • | • | | • | | | • | | • | • | | | |
| DC Block / Coupling | | • | | | | | | | | | • | | • | | • | | |
| Antenna & Impedance Matching | • | | | | | | | | | | | | • | | • | • | |
| RF Filters (e.g. LC, Pi, BPF, LPF) | • | | • | | | | | | | | | | • | • | • | • | |
| Microwave Circuits | • | • | | | | | | | | | | | • | • | • | • | |
| Millimeterwave Circuits | • | • | | | | | | | | | | | | | | | |
| Power Amplifier Matching RF Circuit Matching | • | | | | | | | • | | | | | • | | • | • | • |
| MMIC SubMount | | • | | | | | | | | | | | | | | | |

Collaborative Design Products

Capstrate - Embedded Capacitors



Variable Pitch Capacitors



Unique Geometries

Custom Substrates



k values - 9.3 to 40,000